

Title (en)
SUBSTRATE HOLDING APPARATUS AND POLISHING APPARATUS

Title (de)
SUBSTRATHALTEVORRICHTUNG UND POLIERVORRICHTUNG

Title (fr)
DISPOSITIF DE MAINTIEN DE SUBSTRAT ET APPAREIL DE POLISSAGE

Publication
EP 1625613 A4 20080716 (EN)

Application
EP 04714500 A 20040225

Priority
• JP 2004002219 W 20040225
• JP 2003142276 A 20030520

Abstract (en)
[origin: WO2004105112A1] A substrate holding apparatus holds a substrate such as a semiconductor and presses the substrate against a polishing surface. The substrate holding apparatus includes a top ring body (2) for holding the substrate, a plurality of fluid passages (33, 34, 35, 36) for supplying a fluid to a plurality of pressure chambers (22, 23, 24, 25) defined in the top ring body, and a plurality of sensors (S1, S2, S3, S4) disposed in the fluid passages, respectively, for detecting flowing states of the fluid which flows through the fluid passages.

IPC 8 full level
H01L 21/304 (2006.01); **B24B 37/04** (2012.01); **B24B 37/30** (2012.01); **B24B 37/32** (2012.01); **B24B 49/16** (2006.01); **H01L 21/00** (2006.01); **H01L 21/68** (2006.01)

CPC (source: EP KR US)
B24B 37/30 (2013.01 - EP US); **B24B 49/16** (2013.01 - EP US); **H01L 21/304** (2013.01 - KR); **H01L 21/67092** (2013.01 - EP US); **H01L 21/6838** (2013.01 - EP US)

Citation (search report)
• [X] EP 1240977 A2 20020918 - EBARA CORP [JP]
• [X] US 6435956 B1 20020820 - OHWADA SHIN [JP], et al
• See references of WO 2004105112A1

Designated contracting state (EPC)
DE FR

DOCDB simple family (publication)
WO 2004105112 A1 20041202; CN 100377311 C 20080326; CN 101241843 A 20080813; CN 101241843 B 20121226; CN 1791970 A 20060621; EP 1625613 A1 20060215; EP 1625613 A4 20080716; EP 1625613 B1 20130925; JP 2004349340 A 20041209; JP 4718107 B2 20110706; KR 101044738 B1 20110628; KR 20050121758 A 20051227; TW 200425995 A 20041201; TW I241938 B 20051021; US 2007111637 A1 20070517; US 7465214 B2 20081216

DOCDB simple family (application)
JP 2004002219 W 20040225; CN 200480013867 A 20040225; CN 200810081220 A 20040225; EP 04714500 A 20040225; JP 2003142276 A 20030520; KR 20057021754 A 20040225; TW 93104717 A 20040225; US 55570204 A 20040225